



---

**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16820**Generic Copy

---

**Issue Date:** 04-Jul-2012**TITLE:** PCWB/PCWC/PCWD: Implementation of pre-mold plasma clean**PROPOSED FIRST SHIP DATE:** 04-Oct-2012 or earlier upon customer approval**AFFECTED CHANGE CATEGORY(S):** Assembly process**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or <[filip.thierens@onsemi.com](mailto:filip.thierens@onsemi.com)>**SAMPLES:** Contact your local ON Semiconductor Sales Office**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.**DESCRIPTION AND PURPOSE:**

This is to announce the Implementation of plasma clean operation prior to mold during assembly processing. The purpose is to improve quality of the packaging.

**Qualification data:**

Qualification was performed according to the qualification plan that was announced in IPCN16820. All qualification data are provided in the attached separate qualification report (0PCWC\_DP\_B01.pdf)

**List of affected Customer Specific Parts:**0PCWB-002-XTP  
0PCWC-002-XTP  
0PCWC-003-XTP  
0PCWC-004-XTP  
0PCWC-006-XTP  
0PCWC-007-XTP  
0PCWC-008-XTP  
0PCWD-001-XTP